



Initial Product/Process Change Notification

Document #: IPCN26981XA1

Issue Date: 28 Jul 2026

Title of Change:	Update to IPCN26981XA - Wafer Fab and Probe Site Change for UFET Planar Products from Mountain Top, USA to Bucheon, Korea	
Proposed First Ship date:	25 Jun 2027 or earlier if approved by customer	
Contact Information:	Contact your local onsemi Sales Office	
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact < PCN.Support@onsemi.com >	
Marking of Parts/ Traceability of Change:	The changed material can be identified by lot code and date code	
Change Category:	Assembly Change, Test Change, Wafer Fab Change	
Change Sub-Category(s):	Material Change, Manufacturing Site Transfer	
Sites Affected:		
onsemi Sites	External Foundry/Subcon Sites	
onsemi Bucheon, Korea	None	
onsemi Suzhou, China		
Description and Purpose:		
This Update Notification is to inform customers of the qualification of onsemi Bucheon, Korea facility as NEW wafer fab site for UFET Planar Technology. FPCNs to be issued in March of 2027 with first ship date as referenced above from Bucheon fab. If your FPCN approval will extend beyond the proposed first ship date, provide unit requirements for the unchanged material to your onsemi sales representative no later than May 31, 2026, by NCNR PO (Last order date for unchanged material). These bridge quantities will be limited and will be considered on a first-come, first-serve basis. onsemi will work with customers to facilitate the approval of the FPCNs by providing early samples and matching electrical data upon request, prior to the final PCN notices in March of 2027 to reduce customers' need for additional unchanged material. Early samples are processed according to final process and condition as released in the FPCN. No changes will occur between early samples and after FPCN issuance.		
	Before Change Description	After Change Description
FAB Site	Mountain Top, PA, USA	Bucheon, Korea
Back grind Site	Mountain Top, PA, USA	Bucheon, Korea
Probe Site	Mountain Top, PA, USA and Bucheon, Korea	Bucheon, Korea
Mold Compound change	Showa Denko CEL8240HF10FC	Hysol GR710F
OPN naming	No change	-BK suffix added

Qualification Plan:

QV DEVICE NAME : HUF75852G3

RMS : 98202

PACKAGE : TO-247

Test	Specification	Condition	Interval
High Temperature Reverse Bias	JESD22-A108	Tj = Max rate Tj for device, bias =100% of rated V (Not to exceed max rated)	1,008 hrs
High Temperature Gate Bias	JESD22-A108	Tj = Max rate Tj for device, Max Vgs	1,008 hrs
High Temperature Storage Life	JESD22-A103	Ta =Max rate storage temp for device	1,008 hrs
Highly Accelerated Stress Test	JESD22-A110	Temp = 130C, 85% RH, ~ 18.8 psig, bias = 80% of rated V or 100V max	96 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	Temp = 130C, RH=85%, ~ 18.8 psig	96 hrs
Temp Cycling	JESD22-A104	Temp = -55°C to +150°C	1,000 cyc
Intermittent Operating Life	MIL STD750, M 1037, AEC Q101	Ta=+25°C, deltaTj=100°C max, 5 min Ton=Toff	6,000 cyc

QV DEVICE NAME : RFP70N06

RMS : 98204

PACKAGE : TO-220

Test	Specification	Condition	Interval
High Temperature Reverse Bias	JESD22-A108	Tj = Max rate Tj for device, bias =100% of rated V (Not to exceed max rated)	1,008 hrs
Highly Accelerated Stress Test	JESD22-A110	Temp = 130C, 85% RH, ~ 18.8 psig, bias = 80% of rated V or 100V max	96 hrs
Unbiased Highly Accelerated Stress Test	JESD22-A118	Temp = 130C, RH=85%, ~ 18.8 psig	96 hrs
Temp Cycling	JESD22-A104	Temp = -55°C to +150°C	1,000 cyc

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Current Part Number	New Part Number	Qualification Vehicle
BUZ11-NR4941	BUZ11-NR4941-BK	HUF75852G3
HUF75321D3ST	HUF75321D3ST-BK	HUF75852G3
HUF75321P3	HUF75321P3-BK	HUF75852G3
HUF75329D3ST	HUF75329D3ST-BK	HUF75852G3
HUF75344G3	HUF75344G3-BK	HUF75852G3
HUF75344P3	HUF75344P3-BK	HUF75852G3
HUF75345G3	HUF75345G3-BK	HUF75852G3
HUF75345S3ST	HUF75345S3ST-BK	HUF75852G3



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HUF75339P3	HUF75339P3-BK	HUF75852G3
RFD16N05SM9A	RFD16N05SM9A-BK	HUF75852G3
HUF76639S3ST	HUF76639S3ST-BK	HUF75852G3
HUF76629D3ST	HUF76629D3ST-BK	HUF75852G3
HUF76439S3ST	HUF76439S3ST-BK	HUF75852G3
HUF76423P3	HUF76423P3-BK	HUF75852G3
HUF76407D3ST	HUF76407D3ST-BK	HUF75852G3
HUF75852G3	HUF75852G3-BK	HUF75852G3
HUF75652G3	HUF75652G3-BK	HUF75852G3
HUF75545S3ST	HUF75545S3ST-BK	HUF75852G3
HUF75545P3	HUF75545P3-BK	HUF75852G3
HUF75345P3	HUF75345P3-BK	HUF75852G3
RFP70N06	RFP70N06-BK	HUF75852G3
RFP50N06	RFP50N06-BK	HUF75852G3
RFP12N10L	RFP12N10L-BK	HUF75852G3
RFD3055LESM9A	RFD3055LESM9A-BK	HUF75852G3
RFD14N05SM9A	RFD14N05SM9A-BK	HUF75852G3
RFD12N06RLESM9A	RFD12N06RLESM9A-BK	HUF75852G3
HUF76429S3ST	HUF76429S3ST-BK	HUF75852G3
HUF75645P3	HUF75645P3-BK	HUF75852G3
HUF75639S3ST	HUF75639S3ST-BK	HUF75852G3
HUF75639P3	HUF75639P3-BK	HUF75852G3
HUF75639G3	HUF75639G3-BK	HUF75852G3
HUF75542P3	HUF75542P3-BK	HUF75852G3
RFD16N06LESM9A	RFD16N06LESM9A-BK	HUF75852G3
RFD16N05LSM9A	RFD16N05LSM9A-BK	HUF75852G3
RFD14N05LSM9A	RFD14N05LSM9A-BK	HUF75852G3
RFD14N05LSM	RFD14N05LSM-BK	HUF75852G3